



## Key Features and Benefits

- Transparent potting adhesive with good fluidity
- Fast curing speed and flexible process applicability
- High light transmittance, facilitating visual inspection of components
- 100% solid content, no exudate after curing
- Excellent high and low temperature resistance, superior weatherability, radiation resistance and outstanding dielectric properties
- Stable chemical and mechanical properties

## Description

PAKCOOL® TPC-200-U1 is a 10:1 two-component liquid electronic potting compound, which can be cured at room temperature or under heating. After curing, the product forms a flexible elastomer, suitable for the protection of electrical/PCB components, and features certain repairability. The cured adhesive exhibits low stress, excellent high and low temperature resistance as well as high electrical insulation. Before curing, this product boasts outstanding fluidity and leveling property. It generates no heat during the curing process and cures at a constant rate regardless of potting thickness and sealing degree. No volatile substances are produced after curing, and the curing system of the product possesses excellent poison resistance.

## Applications

- LED lighting encapsulation
- High voltage resistor packs
- Transformers
- Power Module
- Sensors
- Communication Equipment

## Precautions

- Contact of this product with certain substances may cause incomplete or failure of curing. Such substances include: compounds of sulfur, phosphorus and nitrogen (e.g., polysulfone, polysulfide ether, polyurethane, amide and amine-containing substances); substances containing tin, arsenic, antimony, selenium and tellurium; as well as some unsaturated hydrocarbons and plasticizers.
- Due to the slight viscosity difference between Component A and Component B, slight pressure adjustment of Component B is required when adopting automatic potting equipment.

## Technical Parameters

Typical Properties	TPC-200-U1	Test Methods
Base Material	Silicone	--
Color	Colorless and transparent	Visual
Mix Ratio	10:1	--
Viscosity (cP)	A: ≤9000 B: ≤3000	ASTM D2196-20
Operation time (h @25 °C)	≥1 (Adjustable)	--
Tensile Strength (MPa)	≥8.0	ASTM D412
Hardness (Shore A)	45±5	ASTM D2240
Density (g/ cm <sup>3</sup> )	1.03±0.02	ASTM D792
Dielectric Strength (kV/mm)	≥20	ASTM D149
Volume Resistivity (Ω·cm)	≥1.0×10 <sup>15</sup>	ASTM D257
Shelf Life (@ Room Temp)	12 months	--
Continuous Use Temperature (°C)	-50 ~ 150	--

Note: Data is for guidance only and should not be used as product specifications.

## Storage

- PAKCOOL® TPC-200-U1 should be storage in a cool and dry place. Cartridge-based products should be stored horizontally.

## Packaging Specifications

- Available packaging specifications: 500g per can, 5kg per drum and 10kg per drum; customized packaging is available upon customer request.

## Curing Time

- PAKCOOL® TPC-200-U1 can be cure at room temperature for 12h-48h. The crosslinking time will be shortened with the increase of temperature (see table below).

150°C	10 min
70°C	60 min

The data of this specification are obtained under laboratory conditions. However, because of the difference of use environment, process and so on, it can not guarantee the correctness and applicability of the product in some usage and use. When using, be sure to test to confirm the product suitable for your purpose. If you have any problems in using this product, please contact our technical department. We will do our best to help you.